
**Test methods for machine readable
travel documents (MRTD) and
associated devices —**

**Part 1:
Physical test methods for passport
books (durability)**

*Méthodes d'essais pour documents de voyage lisibles par machine et
dispositifs associés —*

*Partie 1: Méthodes d'essais physiques pour livrets de passeport
(durabilité)*

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Foreword

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This document was prepared by Technical Committee ISO/IEC JTC 1, *Information technology*, Subcommittee SC 17, *Cards and security devices for personal identification*.

This second edition cancels and replaces the first edition (ISO/IEC 18745-1:2014), which has been technically revised.

The main changes compared to the previous edition are as follows:

- test definitions have been detailed;
- instructions to evaluate test results have been clarified;
- the definition of the foam to be used in [8.6.4](#) book bend stress method has been changed to enhance the accessibility to the foam needed;
- test sequences have been updated to create more realistic test results;
- references have been updated.

A list of all the parts in the ISO/IEC 18745 series can be found on the ISO website.

Any feedback or questions on this document should be directed to the user's national standards body. A complete listing of these bodies can be found at www.iso.org/members.html.